

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Package Options Include Plastic Small-Outline (DB) Packages and Plastic 300-mil DIPs (N)

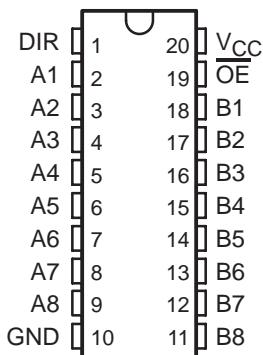
description

The SN74F2245 is designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus depending upon the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input disables the device so the buses are effectively isolated.

Both A and B outputs can sink up to 12 mA; 25- Ω resistors are included in the lower output circuit to reduce overshoot and undershoot.

The SN74F2245 is characterized for operation from 0°C to 70°C.

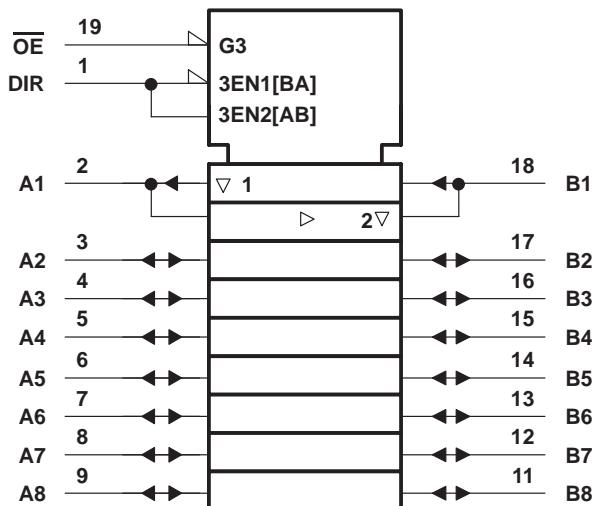
DB OR N PACKAGE
(TOP VIEW)



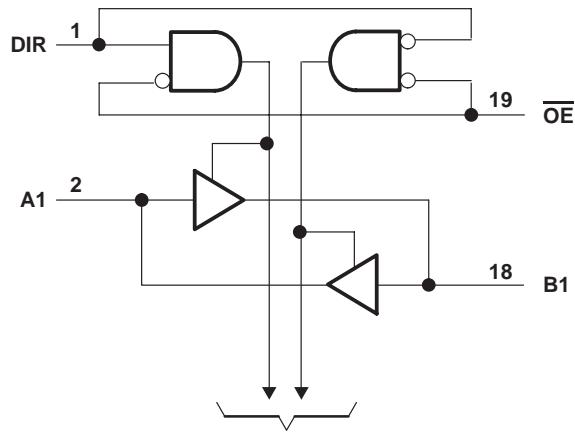
FUNCTION TABLE

INPUTS		OPERATION
\overline{OE}	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

logic symbol[†]



logic diagram (positive logic)



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN74F2245
25- Ω OCTAL BUS TRANSCEIVER
WITH 3-STATE OUTPUTS

SDF099 – MAY 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1)	-1.2 V to 7 V
Input current range	-30 mA to 5 mA
Voltage range applied to any output in the disabled or power-off state	-0.5 V to 5.5 V
Voltage range applied to any output in the high state	-0.5 V to V_{CC}
Current into any output in the low state	30 mA
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range, T_{STG}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I_{IK}	Input clamp current			-18	mA
I_{OH}	High-level output current			-3	mA
I_{OL}	Low-level output current			12	mA
T_A	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [‡]	MAX	UNIT
V_{IK}		$V_{CC} = 4.5$ V, $I_I = -18$ mA				-1.2	V
V_{OH}	Any output	$V_{CC} = 4.5$ V	$I_{OH} = -1$ mA	2.5	3.4		V
			$I_{OH} = -3$ mA	2.4	3.3		
		$V_{CC} = 4.75$ V,	$I_{OH} = -1$ mA to -3 mA	2.7			
V_{OL}	Any output	$V_{CC} = 4.5$ V	$I_{OL} = 1$ mA	0.2	0.5		V
			$I_{OL} = 12$ mA	0.5	0.75		
I_I	A and B	$V_{CC} = 5.5$ V	$V_I = 5.5$ V			1	mA
	DIR and \overline{OE}		$V_I = 7$ V			0.1	
$I_{IH}^§$	A and B	$V_{CC} = 5.5$ V,	$V_I = 2.7$ V	70			μ A
	DIR and \overline{OE}			20			
$I_{IL}^§$	A and B	$V_{CC} = 5.5$ V,	$V_I = 0.5$ V	-0.5			mA
	DIR and \overline{OE}			-0.5			
$I_{OS}^¶$	A and B	$V_{CC} = 5.5$ V,	$V_O = 0$	-50	-120		mA
I_{CC}		$V_{CC} = 5.5$ V	Outputs high	62	90		mA
			Outputs low	73	105		
			Outputs disabled	72	100		

[‡] All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

[§] For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

[¶] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.



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switching characteristics (see Figure 1)

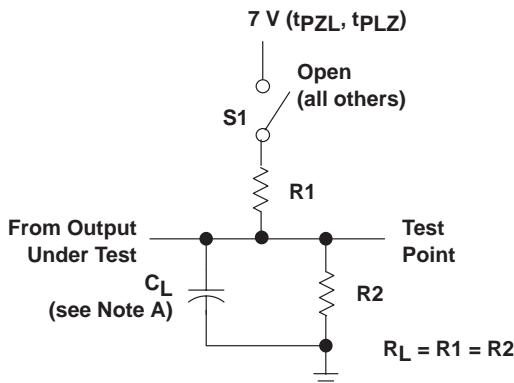
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $R1 = 500\text{ }\Omega$, $R2 = 500\text{ }\Omega$, $T_A = 25^\circ\text{C}$			UNIT	
			MIN	TYP	MAX		
t_{PLH}	A or B	B or A	2.5	3.9	5.5	2.1	6.6
t_{PHL}			3.1	4.6	6.6	2.9	7.1
t_{PZH}	\overline{OE}	A or B	2.4	4.8	7.3	1.6	8.5
t_{PZL}			3.6	6.6	10.6	3	12
t_{PHZ}	\overline{OE}	A or B	2.3	4.3	6.3	2	7.5
t_{PLZ}			2	4	5.8	1.9	6.8

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

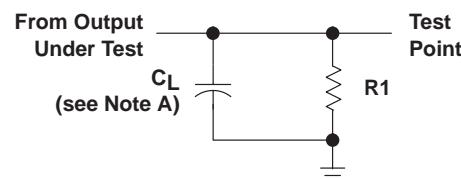
SN74F2245
25- Ω OCTAL BUS TRANSCEIVER
WITH 3-STATE OUTPUTS

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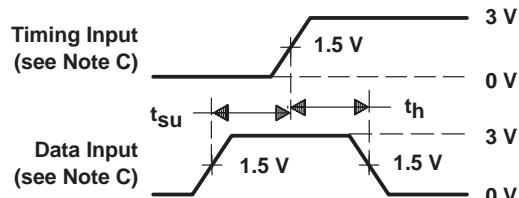
PARAMETER MEASUREMENT INFORMATION



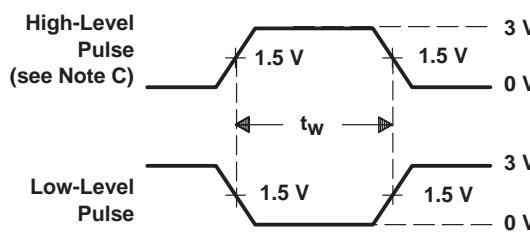
LOAD CIRCUIT FOR
 3-STATE AND OPEN-COLLECTOR OUTPUTS



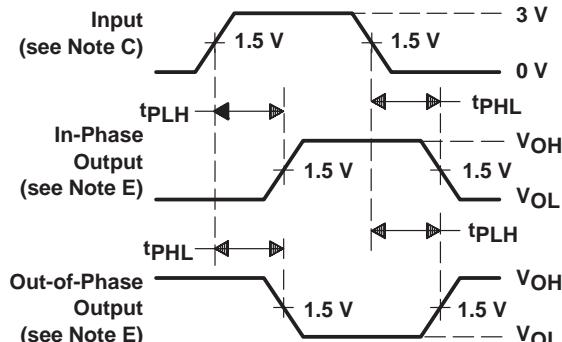
LOAD CIRCUIT FOR
 TOTEM-POLE OUTPUTS



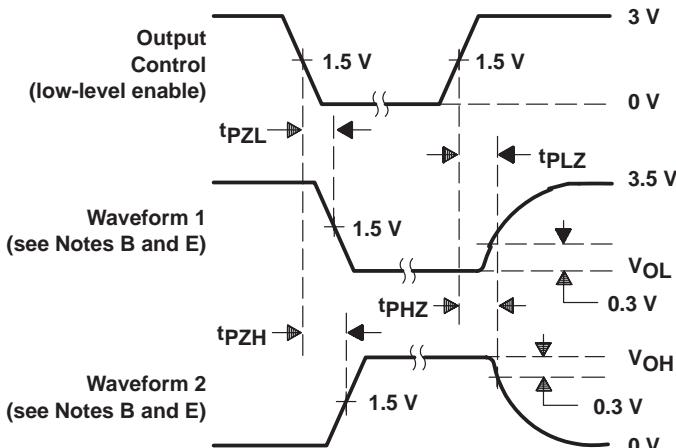
VOLTAGE WAVEFORMS
 SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
 PULSE DURATION



VOLTAGE WAVEFORMS
 PROPAGATION DELAY TIMES (see Note D)



VOLTAGE WAVEFORMS
 ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $t_r = t_f \leq 2.5$ ns, duty cycle = 50%.
 D. When measuring propagation delay times of 3-state outputs, switch S1 is open.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74F2245DBR	OBsolete	SSOP	DB	20		TBD	Call TI	Call TI
SN74F2245DW	OBsolete	SOIC	DW	20		TBD	Call TI	Call TI
SN74F2245DWR	OBsolete	SOIC	DW	20		TBD	Call TI	Call TI
SN74F2245N	OBsolete	PDIP	N	20		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

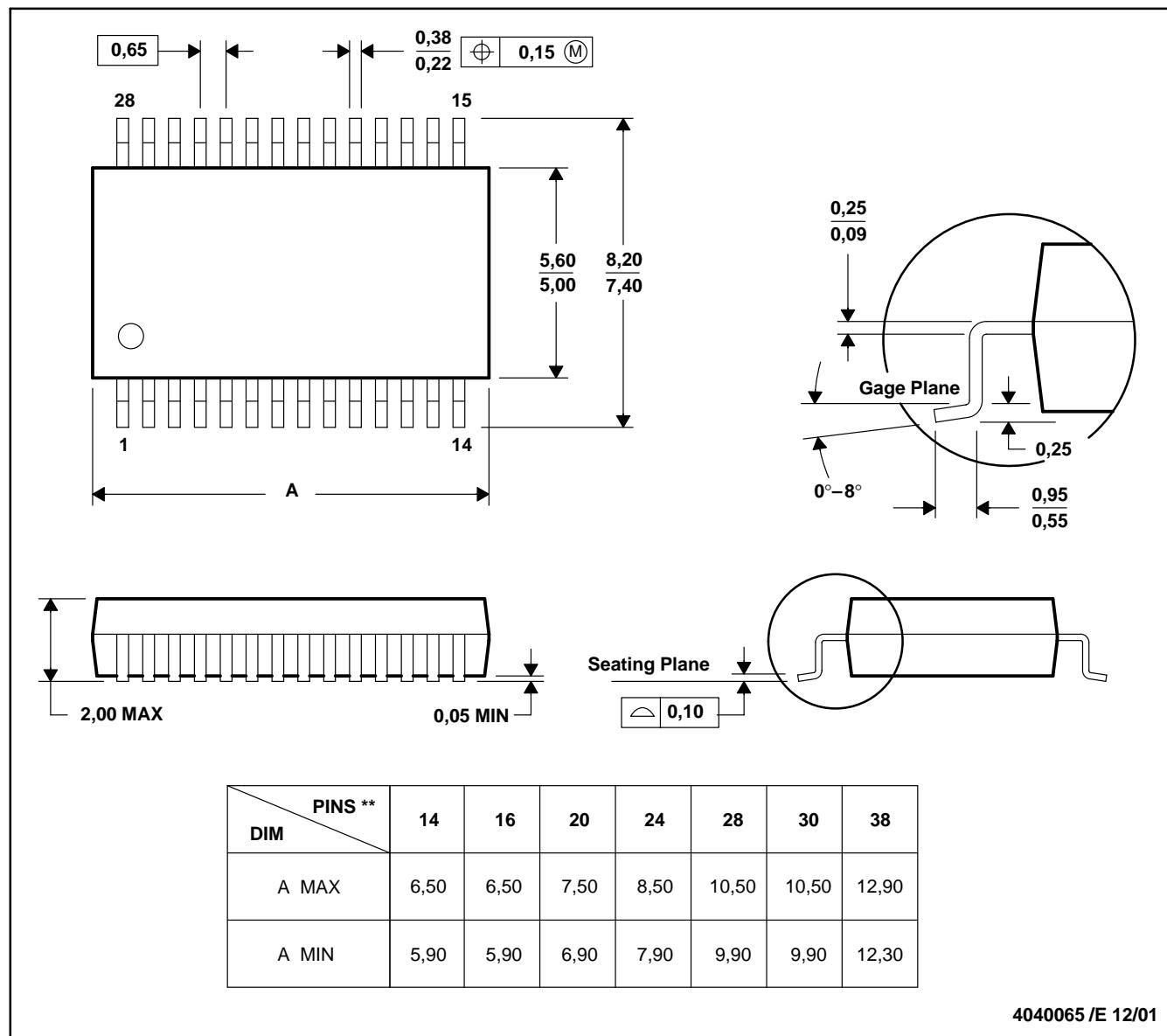
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DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

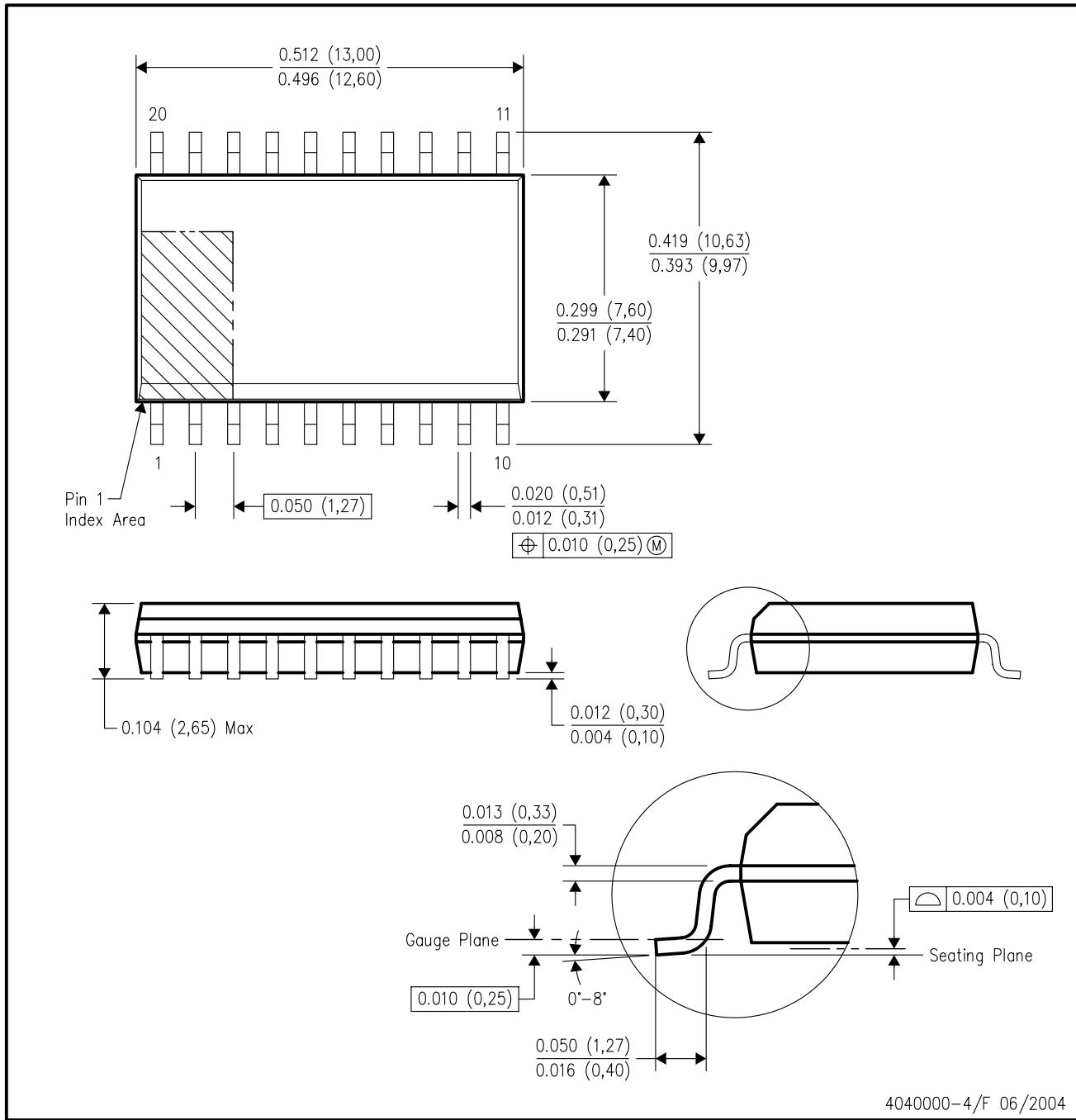
28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



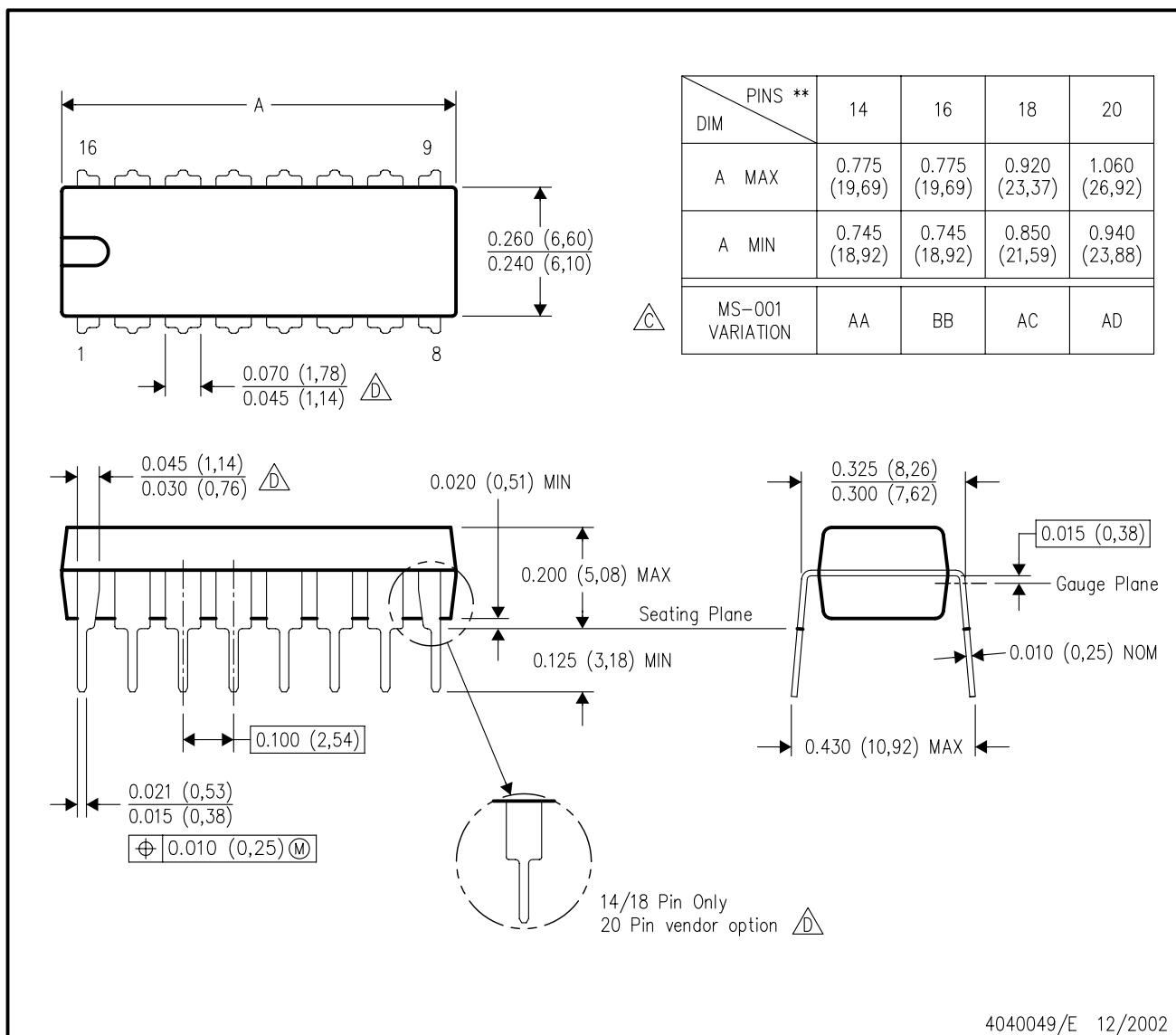
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- Falls within JEDEC MS-013 variation AC.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.

△ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

△ The 20 pin end lead shoulder width is a vendor option, either half or full width.

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